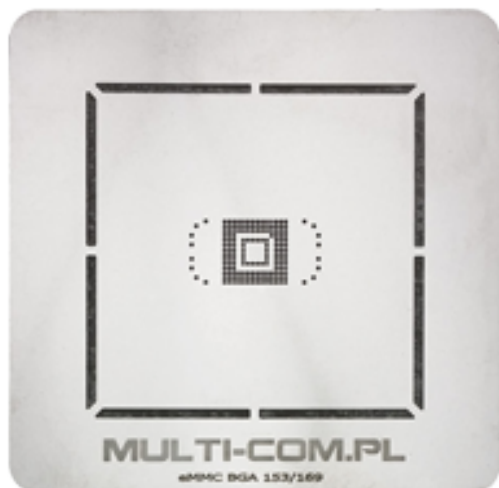


[Main page](#) > [Repair Equipment](#) > [Soldering Equipment](#) > [Stencil BGA kit](#) > [Stencil Direct BGA for eMMC 153/169](#)



## Stencil Direct BGA for eMMC 153/169

Product ID: 21690

Price: **8.00 EUR**

Product weight: **0.01 kg**

### Description:

Stencil Direct BGA for eMMC 153/169 is used for rebailing BGA memory eMMC chips found in phones and tablets.

#### Contact details:

Telefon: +48 17 227 00 25  
Infolinia: 0 801 671 717  
E-mail: [biuro@multi-com.pl](mailto:biuro@multi-com.pl)  
Skype: Multi-COM

#### Address:

Multi-COM Sp. z o.o.  
ul. Stanisława Krzaklewskiego 31b  
36-100 Kolbuszowa  
POLSKA

[Go to the product](#)

